

Table 3. List of Materials

REF DES	27010	27210	DESCRIPTION	MFR	PART NUMBER
	QTY	QTY			
C1, C2, C3, C4, C5	5	5	Capacitor, ceramic, 0.1 μ F, 10 V, X5R, 402	Murata	GRM155R61A104KA01D
D1, D3	2	2	Diode, Zener, 5.6 V, 350 mW, SOT23	Diodes, Inc.	BZX84C5V6T
D2	1	1	Diode, Dual, Zener, 5.6 V, 300 mW, SOT23	Diodes, Inc.	AZ23C5V6
Q1	1	1	MOSFET, N-channel, 2N7002, 60 V, 250 mA, 3 Ω , SOT23	Vishay-Siliconix	2N7002E
Q2	1	1	MOSFET, P-channel, ZVP3306, -60 V, 0.09 A, 14 Ω , SOT23	Zetex	ZVP3306
R1, R2, R11	3	3	Resistor, chip, 100 Ω , 1/16 W, 5%, 603	Std	Std
R13, R14, R16	3	3	Resistor, chip, 1 M Ω , 1/16 W, 5%, 603	Std	Std
R12	1	1	Resistor, chip, 100 k Ω , 1/16 W, 5%, 603	Std	Std
R3, R6, R7	3	3	Resistor, chip, 1 k Ω , 1/16 W, 5%, 402	Std	Std
R4, R5, R9, R10	4	4	Resistor, chip, 100 Ω , 1/16 W, 5%, 402	Std	Std
R17, R18	0	2	Resistor, chip, 15 k Ω , 1/16 W, 5%, 603	Std	Std
R15	1	1	Resistor, chip, 10k Ω , 1/16 W, 5%, 402	Std	Std
R8	1	1	Resistor, chip, 0.02 Ω , 0.25 W, 1%, 1206	Vishay	WSL1206
U1	1	0	Single cell Li-Ion/Polymer gas gauge device, QFN	Texas Instruments	bq27010DRK
U1	0	1	Single cell Li-Ion/Polymer gas gauge device, QFN	Texas Instruments	bq27210DRK
J1, J3	2	2	Terminal blocks, 3 position	OST	ED1515
J2	1	1	Terminal blocks, 2 position	OST	ED1514
J4	0	1	Header, 2-pin, 100mil spacing, (36-pin strip)	Sullins	PTC36SAAN
N/A	1	1	PCB	Any	HPA212

6 bq27x10EVM Circuit Module Performance Specification Summary

Table 4 gives the performance specifications of the bq27x10EVM circuit module.

Table 4. Performance Specification Summary

SPECIFICATION	MIN	TYP	MAX	UNIT
Input Voltage PACK+/BAT-	2.6		4.5	V
Charge and Discharge Current ⁽¹⁾			2.5	A

⁽¹⁾ Charge and discharge maximum is limited by the PCB design and power dissipation of the 20-m Ω 1/4-W sense resistor included in the kit.

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